



DYNATRON

The Thermal Solution Architect

WWW.DYNATRON-CORP.COM

Product Spec Sheet

B4

Application :

- Recommend for Intel® Xeon® Platinum / Gold Family Processor (Products formerly Skylake), Socket FCLGA3647
- **For Narrow ILM Only**
- Passive Cooler for 1U Server

Overall Specification :

- Dimension: 108 x 81 x 27 mm
- Weight: 460 g
- Material: Copper1100 Stacked Fin Heatsink with Vapor Chamber Base
- Convenient Heat Sink Screw captive mounting
- Thermal Grease Shin-Etsu 7762 Pre-printed
- Support CPU power up to 205 Watts heat dissipation
- Includes both Fabric and Non-Fabric Package Carriers

Passive Cooler B4 Thermal Performance Curve

